

Claims

- [c1] A package for receiving connectors comprising a base defining a plurality of receiving zones, at least one of the receiving zone defining a soleplate having a slick upper plane and a lower plane; wherein the lower plane further defines a plurality of bulges thereon to make the lower plane coarse.
- [c2] The package as described in claim 1, wherein each the receiving zone further defines a plurality of supporting bars therein for carrying the connector.
- [c3] The package as described in claim 1, wherein the base is elongated.
- [c4] A connector package for receiving connectors therein for transportation comprising a base defining a plurality of receiving zones, at least one of the receiving zones defining a soleplate having an upper surface and a lower surface, wherein the lower surface is uneven.
- [c5] The connector package as described in claim 4, wherein each of the receiving zones further defines a plurality of supporting bars therein for carrying the connector.

- [c6] The connector package as described in claim 4, wherein the lower surface further defines a plurality of bulges thereon.
- [c7] The connector package as described in claim 4, wherein the upper surface of the soleplate is a plane surface.
- [c8] A package assembly comprising:
a plurality of packages intimately stacked with one another, each of said packages including:
a base defining a plurality of receiving zones each defining a rectangular configuration thereof;
each of said receiving zone including a bottom plate;
a plurality of electronic components disposed in the corresponding receiving zones, respectively; and
an upward plane provided on a top portion of each of said electronic components; wherein
a plurality of visible protrusions are formed on a bottom face of the corresponding bottom plate and extend downwardly toward the corresponding electronic component disposed in the corresponding receiving zone of another base located under said base under a condition that the receiving zones of said base are essentially vertically aligned with those of said another base, so as to sufficiently space the bottom face of the corresponding bottom plate and the upward plane of said corresponding electronic component thereunder without improper

suction occurring therebetween, even when said corresponding bottom plate is forcibly deflected downwardly toward said corresponding electronic component during an automation pick-up process of another electronic component which is disposed in the corresponding zone and located right above said corresponding bottom plate.

- [c9] The package assembly as described in claim 8, wherein said protrusions are relatively far spaced from one another horizontally compared with sizes of said protrusions.